



System-on-chip Fault-Tolerance: the DeSyRe approach

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RECORE

DeSyRe
on-Demand System Reliability

Technology trends

As Technology Scales chips are becoming less reliable

- Harder to keep defect density constant
 - **Manufacturing cost increases**
- Variations become more severe
- Transistor aging is accelerated
- Soft-error rate grows exponentially
 - **mostly logic state bits**

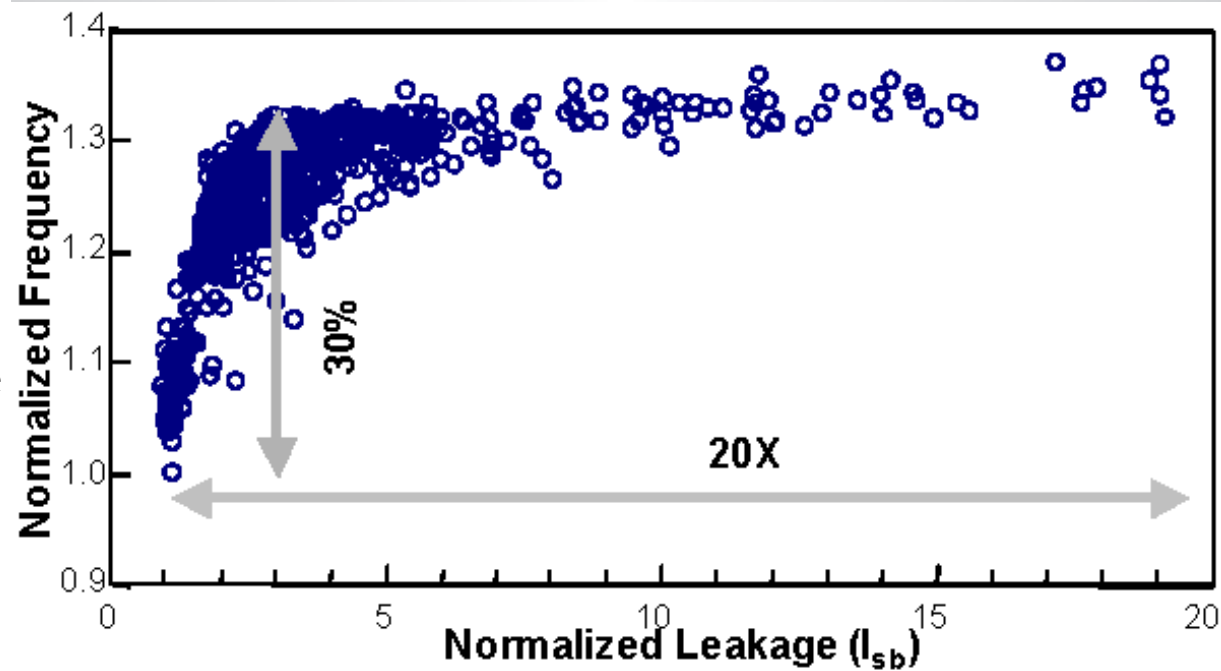
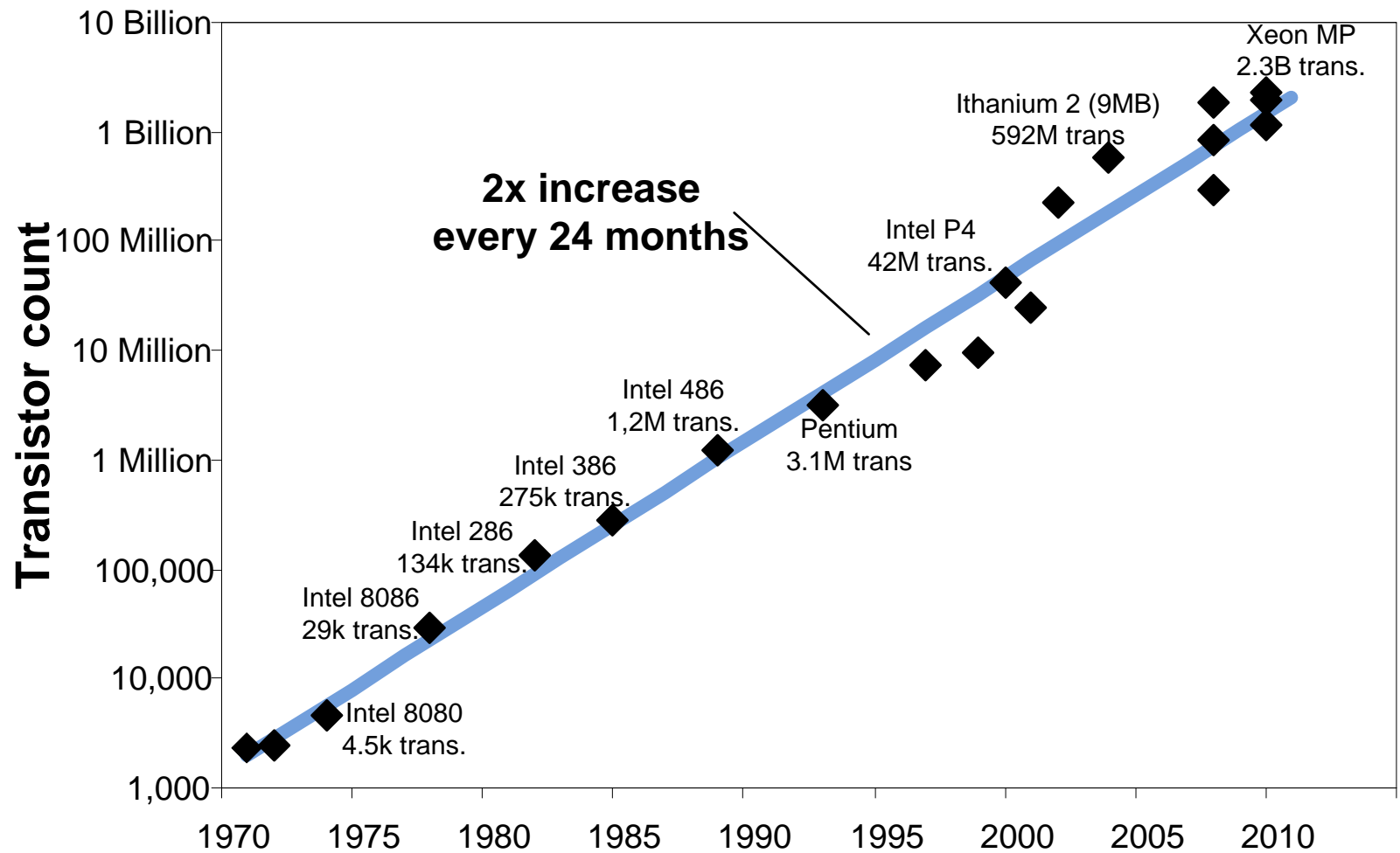


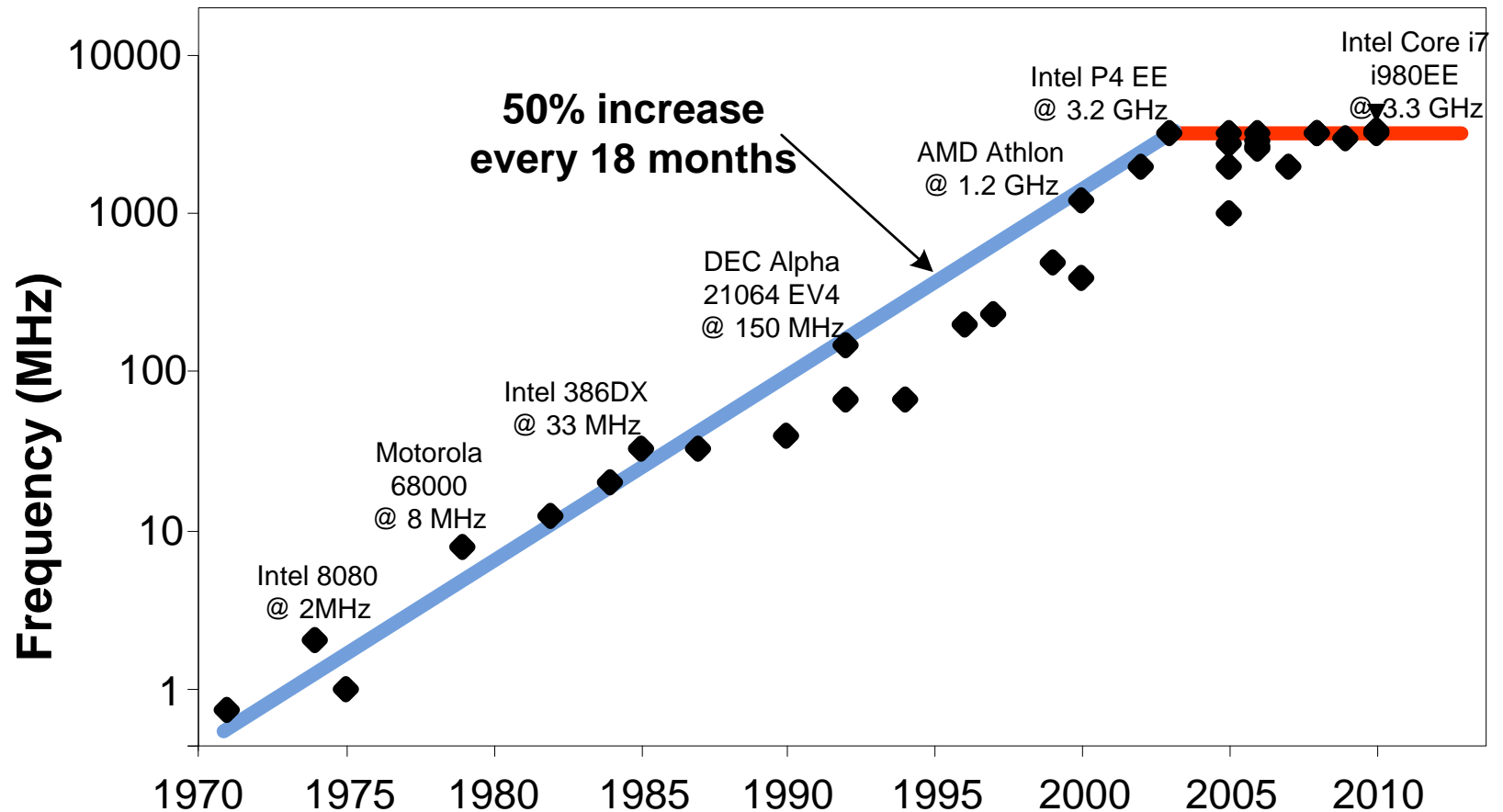
Figure 5. Soft-Transistor's Saturation current (logic and memory).

Transistor count



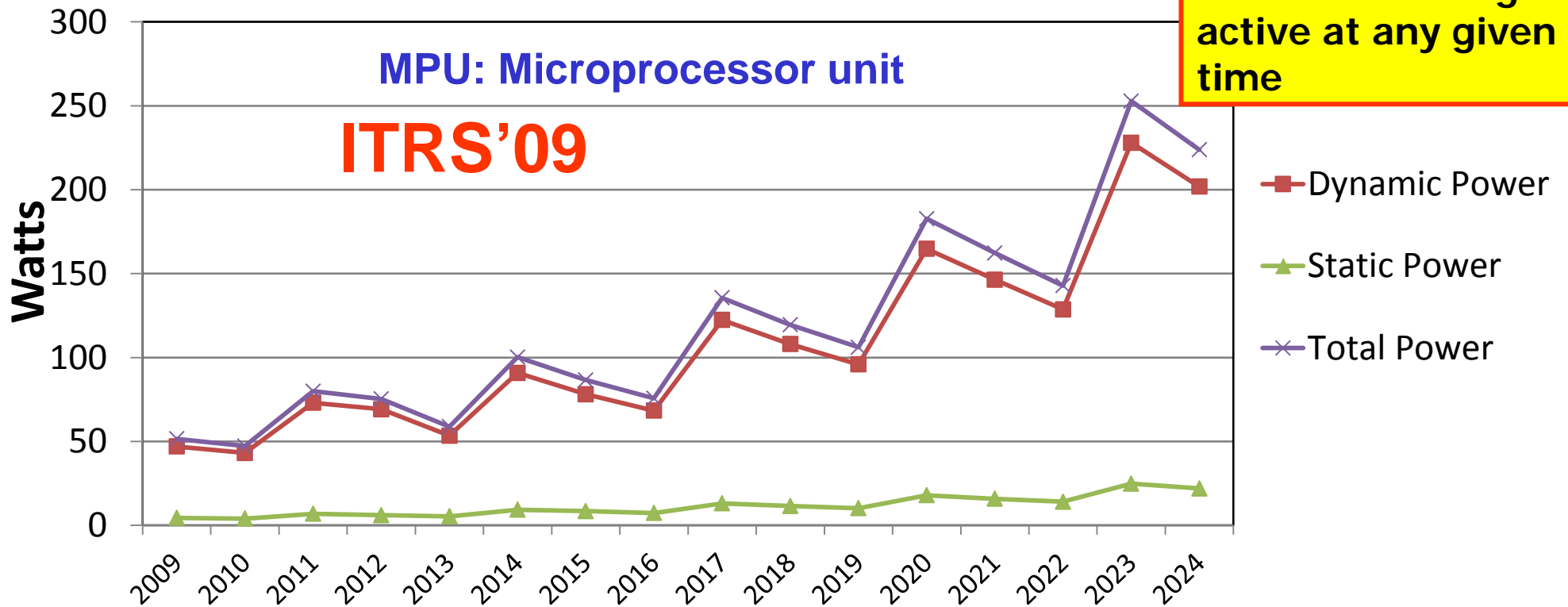
- On-chip resources keep increasing

Performance trends



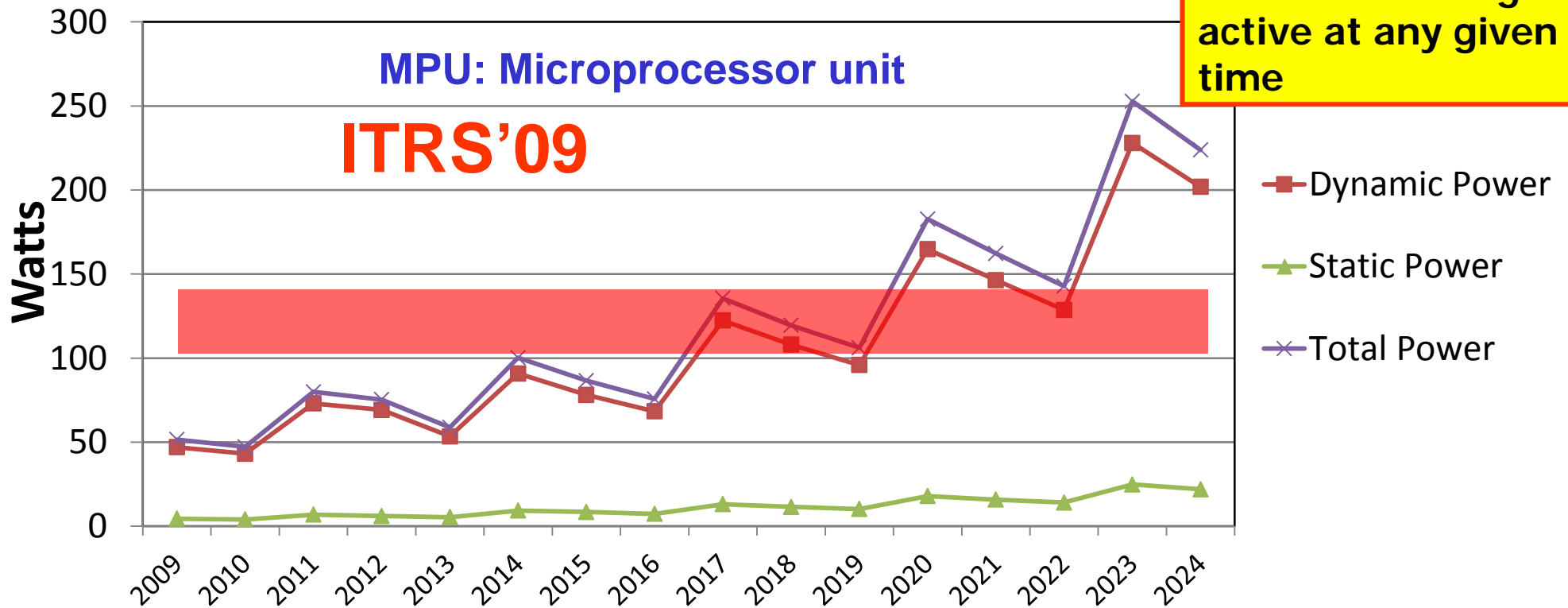
- New technology nodes do not deliver significant Performance improvements

Power trends



- Power consumption is a major limiting factor

Power density limits gate density



- **By 2018 chips will exceed the max allowed power consumption:**

- Then significant parts of a chip will need to be inactive to stay within the available power budget

The Cost of Fault Tolerance

Fault Tolerance requires Redundancy

- **in time:**
 - **Performance** overhead
- **in space:**
 - **Power** and **Area** overhead
- **Both in time and space:**
 - **Energy** overhead



DeSyRe: on-Demand System Reliability

- Generic design framework for future reliable SoCs
- **Main Goal:**
 - to reduce the costs for fault tolerance
- **How?**
 - Flexibility/reconfigurability
 - System-level support for dynamic adaptation
- **Applications:** DeSyRe will be applied to two Medical SoCs



DeSyRe objectives

Develop a generic design framework for heterogeneous embedded SoCs, to:

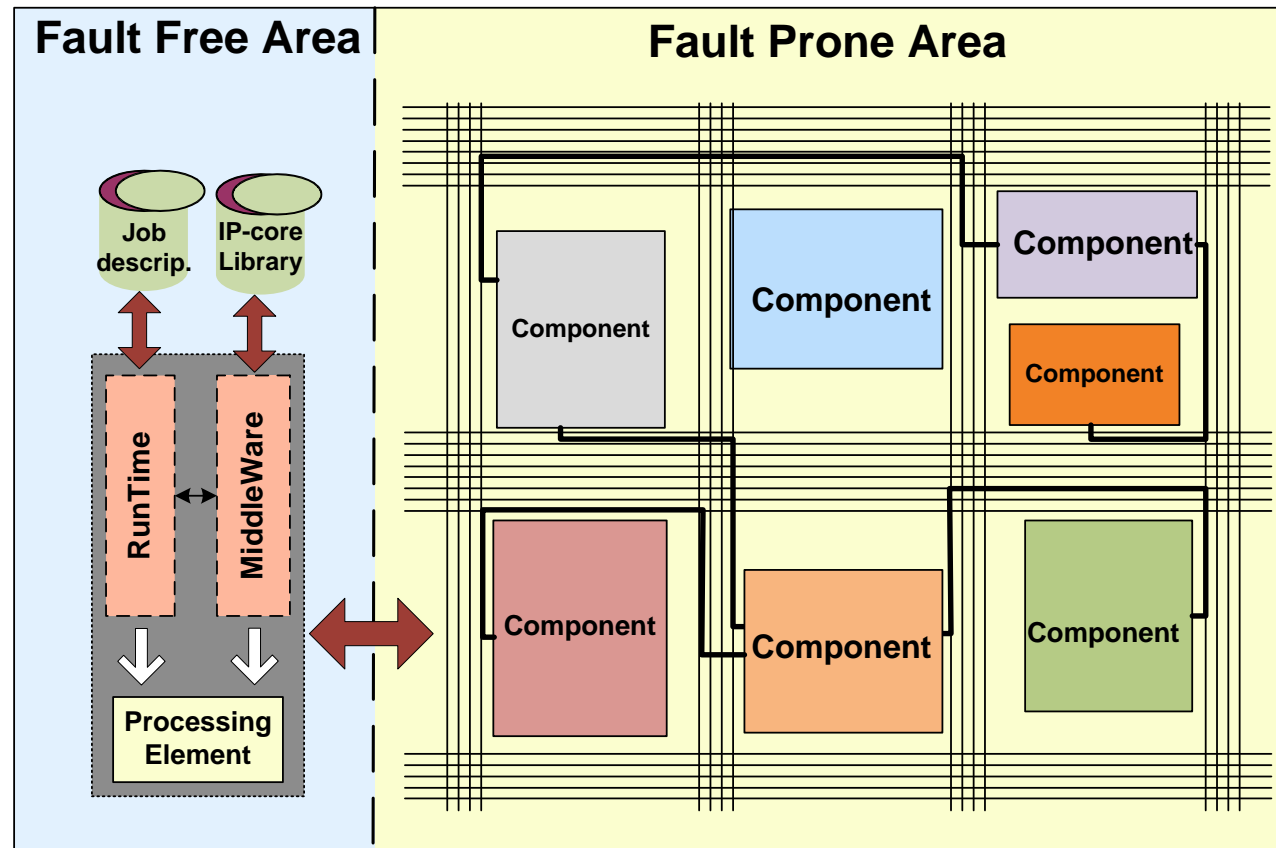
- 1. Provide reliability at a reduced performance, energy and power cost.**
 - tolerate permanent, intermittent and transient faults
- 2. Reliable by Design** (for fabless chip developers)
 - Guarantee reliability of chips by design
 - Technology independent
- 3. Build on-demand adaptive systems.** Systems built on flexible/reconfigurable hardware complimented by system-level techniques. Adaptive to
 - **Various types of faults**
 - **System constraints** (power, energy, resources)
 - **Application requirements** (performance constraints, reliability requirements/safety/availability)
- 4. Increased Defect tolerance** (design, manufacturing defects, defects due to aging).
 - Increased manufacturing yield
 - Longer SoC lifetime
 - Lower manufacturing cost
 - Shorter time-to-market



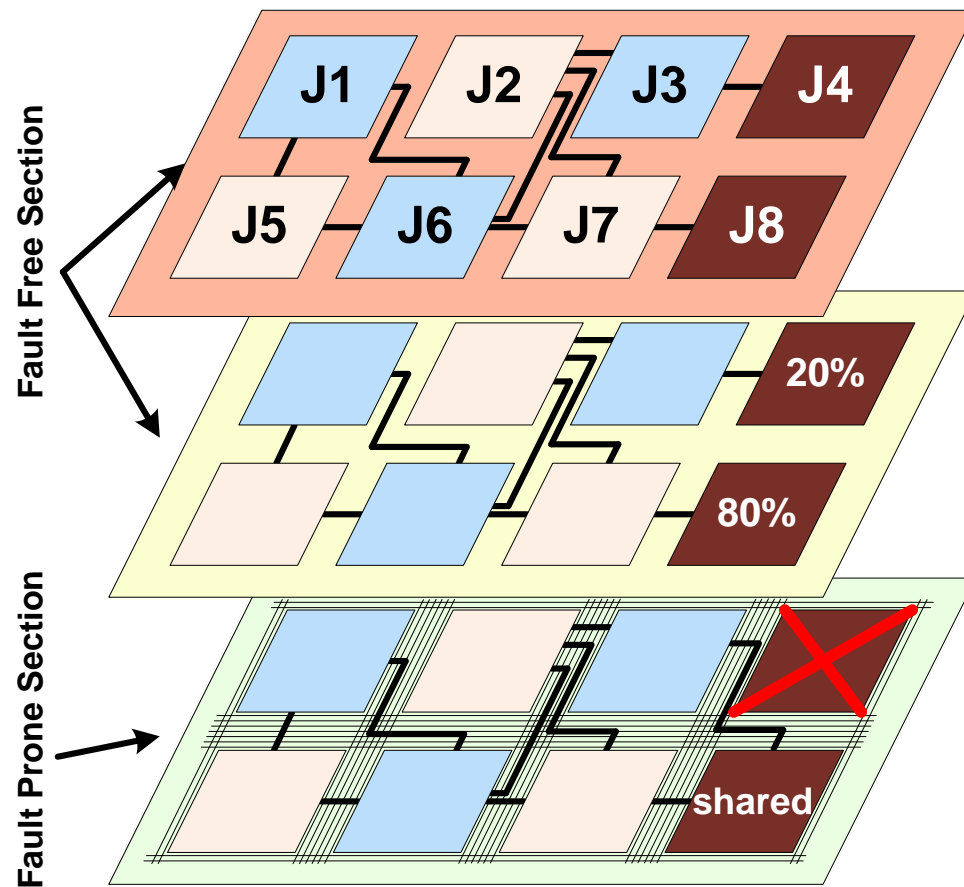
The DeSyRe design framework

- Only a small fraction of the chip will be designed to be **Fault Free**.
 - To **Reduce Cost for Fault Tolerance**
- Fault Free part will manage the remaining unreliable resources.
- The remaining **Fault Prone resources** will provide **flexibility reconfiguration**
- System reliability managed at **runtime** based on the:
 - Application requirements
 - System constraints
 - Fault types and density

System-on-Chip



DeSyRe framework layers



Runtime System
Software-layer

MiddleWare
Software-layer

Components:

1. Component Architecture
2. Realization (HW Substrate)

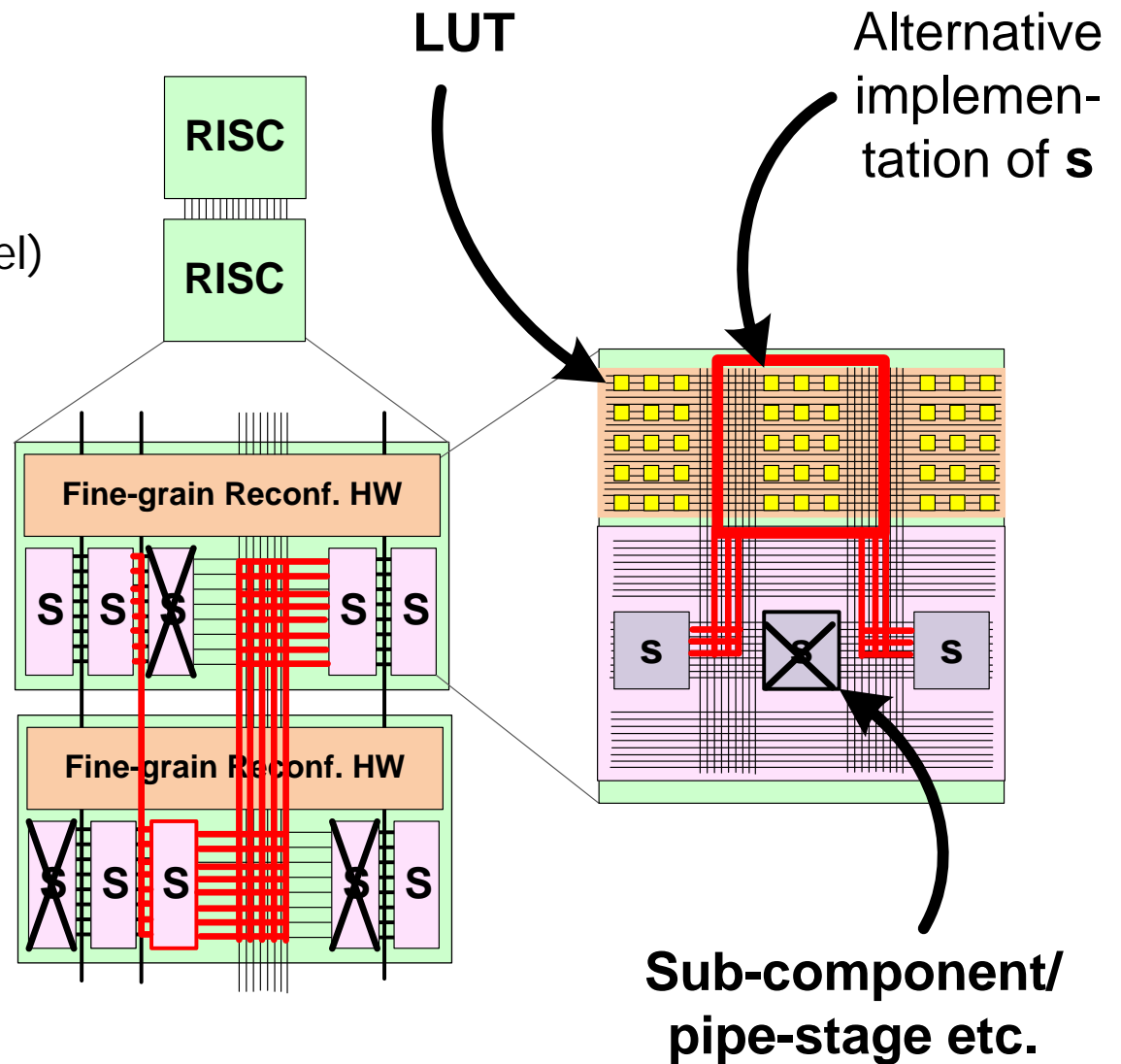
DeSyRe Reconfigurable Substrate

Two levels of Reconfiguration:

1. Coarse-grain (Component-level)
2. Fine-grain (FPGA-like)

Example: RISC processor

- partitioned in pipeline stages
- Reconfigurable wires for interconnection
- Fine-grain reconfigurable blocks



Fault Types: causes / DeSyRe solutions

■ Permanent faults:

- Cause:
 - Manufacturing process or Aging
- Detection (diagnosis):
 - Online and offline testing managed by the fault-free part (or even locally)
- Correction:
 - System Reconfiguration: isolate, replace/task migration /reconfigure

■ Intermittent Faults:

- Cause: variations (process, temperature, etc.)
- Detection: same as transient (+ extra step to distinguish from transient)
- Correction:
 - **1st step: same as transient**
 - **2nd step: similar to permanent (mostly task-migration)**

■ Transient Faults:

- Cause:
 - Radiation, α -particles, etc
- Detection:
 - Local checkers per tile
 - Checkpoints set by the fault-free part
- Correction:
 - Checkpointing (HW assisted): recover and re-execute
 - based on the application needs
 - ECCs



Applications

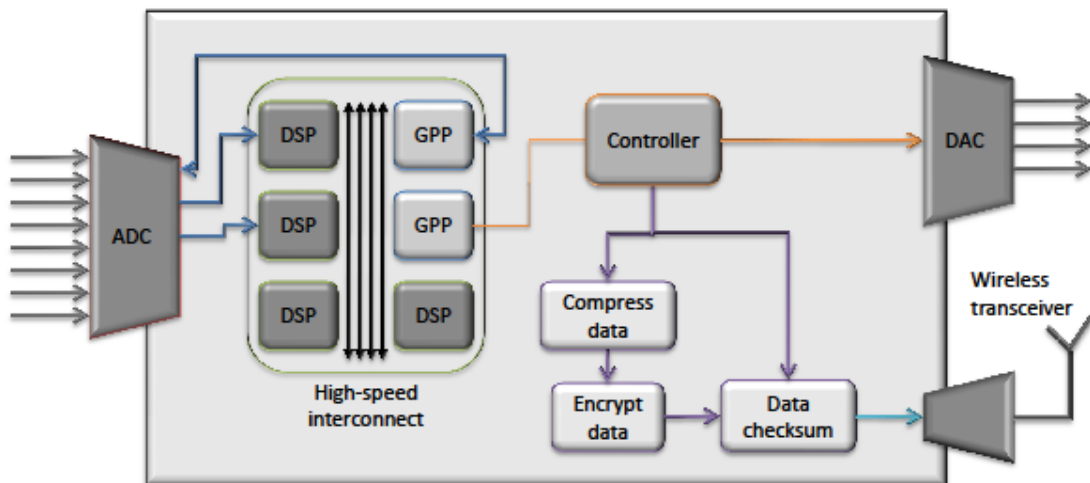
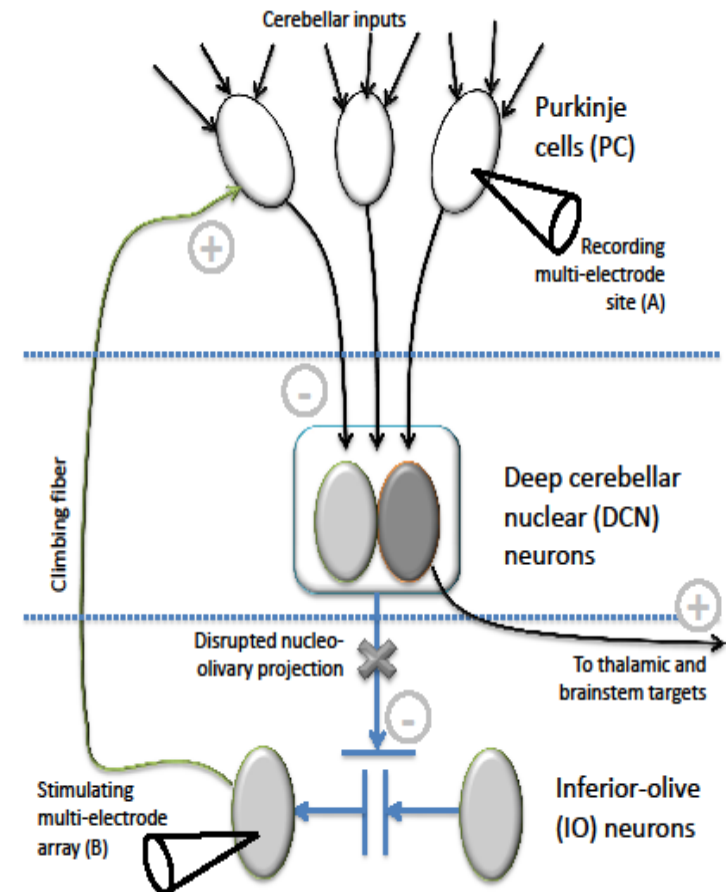
■ Two Medical SoCs

- Applications provided by Neurasmus BV
 - Implantable Artificial Pancreas
 - Wearable Artificial Cerebellum
- Very high reliability constraints
- Different power efficiency requirements
- Different processing requirements



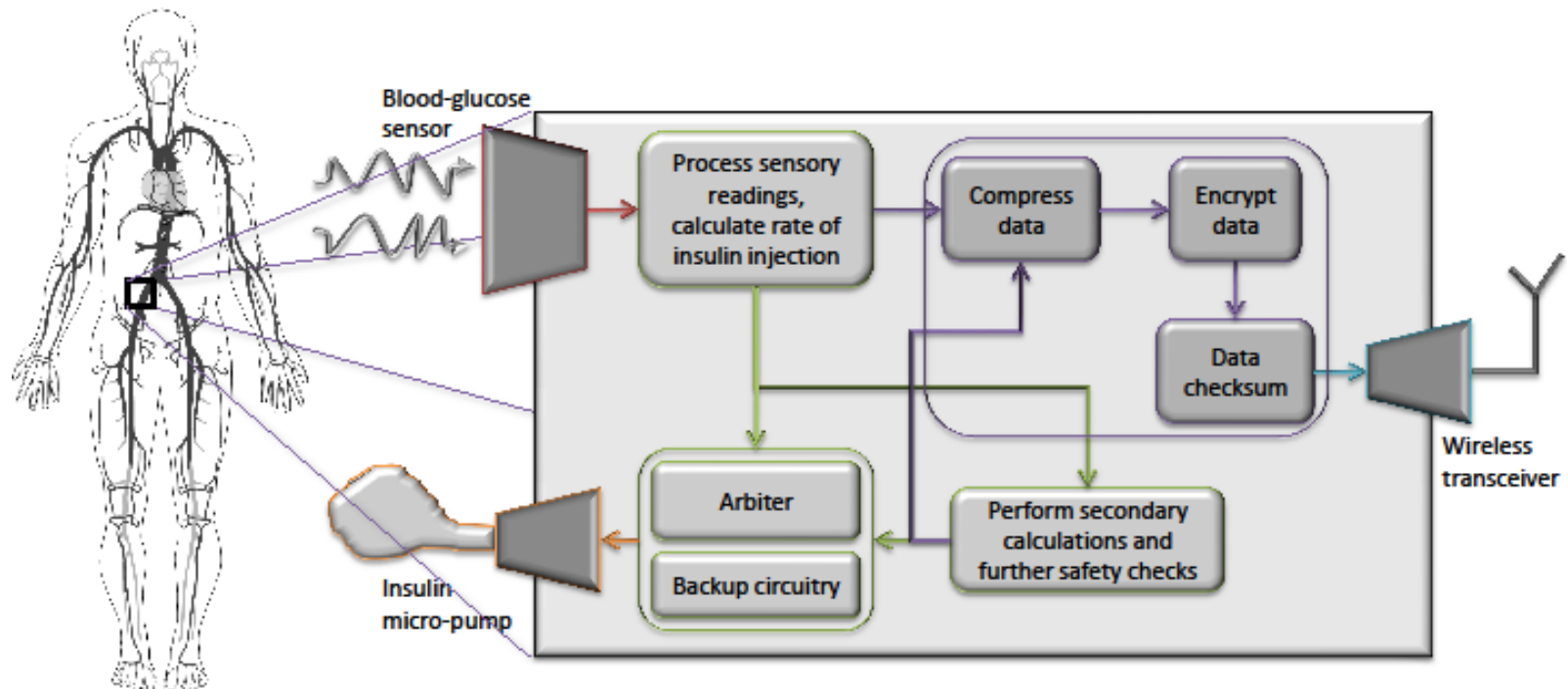
Artificial Cerebellum

- Replace damaged parts of the brain cerebellum
 - **recovering sensorimotor control**
- Build an artificial cerebellar system
 - **Multi-level, closed-loop control**
 - Use **Deep-Cerebellar-Nuclear-Neuron models** to artificially compute the output of the replaced part.



- Realtime constraints:
 - **Low latency**
 - **High throughput**
- High reliability
- Power efficiency
- Adaptive to different input patterns

Artificial Pancreas



- Glucose-level sensing
- Control insulin injection
- Lightweight processing
- Ultra-low power
- Wireless (and secure) user interface

Conclusions

- DeSyRe will describe a design framework for reliable future SoCs
 - **Lowering the cost of Fault tolerance**
 - **Power**
 - **Energy,**
 - **Performance**
- On-demand adaptation to
 - Fault types and densities
 - System constraints
 - Application requirements
- DeSyRe SoCs will exploit
 - The flexibility of a reconfigurable substrate
 - Runtime System support for adaptation



Thank you!
Questions?

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